





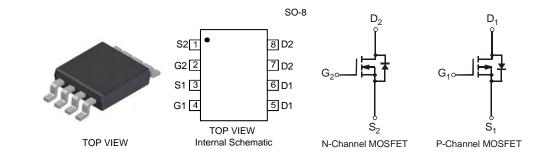
COMPLEMENTARY PAIR ENHANCEMENT MODE MOSFET

Features

- Complementary Pair MOSFETs
- Low On-Resistance
 - N-Channel: 35mΩ @ 10V 61mΩ @ 4.5V
 - P-Channel: 65mΩ @ -10V
 - 115mΩ @ -4.5V
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Lead Free By Design/RoHS Compliant (Note 2)
- "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 6
- Ordering Information: See Page 6
- Weight: 0.072g (approximate)



Maximum Ratings N-CHANNEL @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Drain Source Voltage	V _{DSS}	30	V
Gate-Source Voltage	V _{GSS}	±20	V
Drain Current (Note 1) $T_A = 25^{\circ}C$ $T_A = 70^{\circ}C$		6.9 5.8	А
Pulsed Drain Current (Note 4)	I _{DM}	30	А

Maximum Ratings P-CHANNEL @T_A = 25°C unless otherwise specified

Char	acteristic	Symbol	Value	Unit
Drain Source Voltage		VDSS	-30	V
Gate-Source Voltage		V _{GSS}	±20	V
Drain Current (Note 1)	T _A = 25°C T _A = 70°C	ID	-5 -4.2	А
Pulsed Drain Current (Note 4)		I _{DM}	-20	A

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	PD	2	W
Thermal Resistance, Junction to Ambient	$R_{ extsf{ heta}JA}$	62.5	°C/W
Operating and Storage Temperature Range	T _j , T _{STG}	-55 to +150	°C

Notes: 1. Device mounted on 2oz. copper pads on 2" x 2" FR4 PCB.

2. No purposefully added lead.

3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.

4. Repetitive rating, pulse width limited by junction temperature.



Test Condition

Electrical Characteristics N-CHAN	INEL @	@T _A = 25°C	unless othe	erwise spec	ified	
Characteristic	Symbol	Min	Тур	Max	Unit	

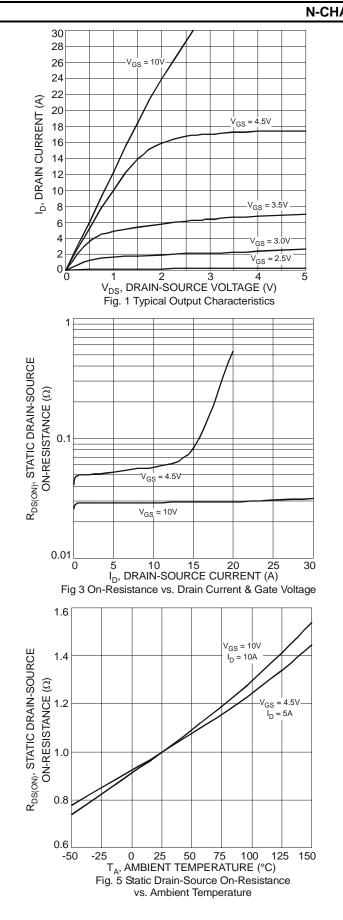
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV _{DSS}	30			V	$V_{GS} = 0V, I_D = 250 \mu A$
Zero Gate Voltage Drain Current	I _{DSS}		_	1	μΑ	$V_{DS} = 24V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	± 100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	V _{GS(th)}	1	_	2.1	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
Static Drain-Source On-Resistance	R _{DS (ON)}		28 51	35 61	mΩ	V _{GS} = 10V, I _D = 6.9A V _{GS} = 4.5V, I _D = 5.0A
Forward Transfer Admittance	Y _{fs}	_	7.7	_	S	$V_{DS} = 5V, I_D = 6.9A$
Diode Forward Voltage (Note 5)	V _{SD}	0.5	_	1.2	V	$V_{GS} = 0V, I_S = 1A$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	_	384	_	pF	
Output Capacitance	Coss	_	67	_	pF	V _{DS} = 15V, V _{GS} = 0V, f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	48	_	pF	
Gate Resistance	Rg	_	1.3	_	Ω	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$
SWITCHING CHARACTERISTICS					•	
Total Gate Charge	Qg		4.3 8.6	_		$V_{DS} = 10V, V_{GS} = 4.5V, I_D = 10A$ $V_{DS} = 10V, V_{GS} = 10V, I_D = 10A$
Gate-Source Charge	Q _{gs}		1.2		nC	V _{DS} = 10V, V _{GS} = 10V, I _D = 10A
Gate-Drain Charge	Q _{gd}		2.5			$V_{DS} = 10V, V_{GS} = 10V, I_D = 10A$

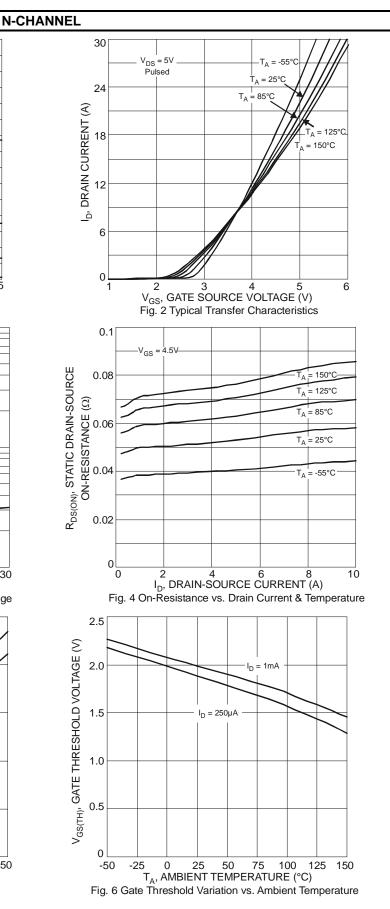
Electrical Characteristics P-CHANNEL @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)					1	
Drain-Source Breakdown Voltage	BV _{DSS}	-30		_	V	$V_{GS} = 0V, I_D = -250 \mu A$
Zero Gate Voltage Drain Current	I _{DSS}		_	-1.0	μΑ	$V_{DS} = -24V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_	_	± 100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	V _{GS(th)}	-1	_	-2.1	V	$V_{DS} = V_{GS}, I_D = -250 \mu A$
Static Drain-Source On-Resistance	R _{DS (ON)}	_	56 98	65 115	mΩ	V _{GS} = -10V, I _D = -5A V _{GS} = -4.5V, I _D = -4A
Forward Transfer Admittance	Y _{fs}		_	5.2	S	$V_{DS} = -10V, I_{D} = -5A$
Diode Forward Voltage (Note 5)	V _{SD}	-0.5	_	-1.2	V	$V_{GS} = 0V, I_{S} = -2.6A$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	_	336		pF	
Output Capacitance	Coss	_	70		pF	$V_{DS} = -25V, V_{GS} = 0V, f = 1.0MHz$
Reverse Transfer Capacitance	C _{rss}	_	49		pF	
Gate Resistance	R _G	_	4.6		Ω	$V_{GS} = 0V, V_{DS} = 0V, f = 1MHz$
SWITCHING CHARACTERISTICS						-
Total Gate Charge	Qg	—	4.0 7.8	_	. 0	$V_{DS} = 15V, V_{GS} = -4.5V, I_D = -5A$ $V_{DS} = 15V, V_{GS} = -10V, I_D = -5A$
Gate-Source Charge	Q _{gs}	_	1.0	—	nC	V _{DS} = 15V, V _{GS} = -10V, I _D = -5A
Gate-Drain Charge	Q _{qd}	_	2.5		1	V _{DS} = 15V, V _{GS} = -10V, I _D = -5A

Notes: 5. Short duration pulse test used to minimize self-heating effect.







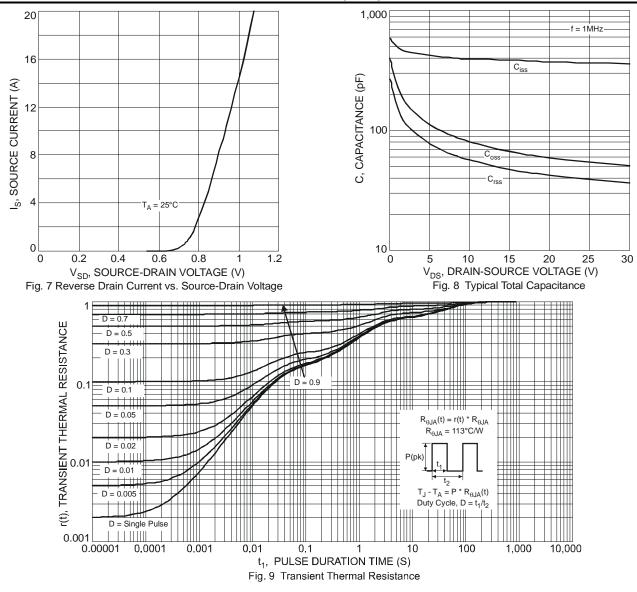
DMC3035LSD Document number: DS31312 Rev. 5 - 3 Downloaded from Arrow.com.



Not Recommended for New Design, Use DMC3036LSD-13

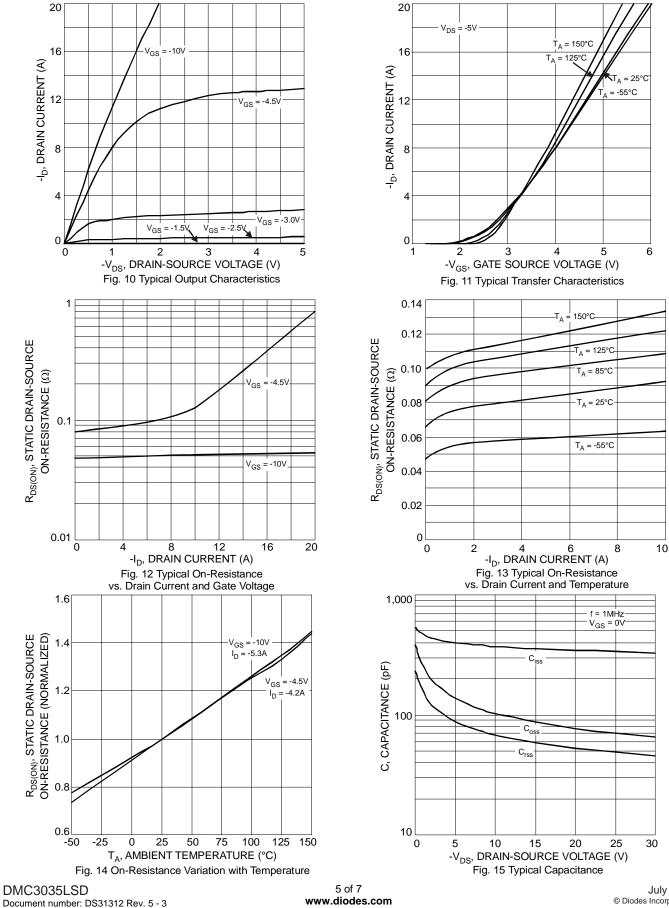
DMC3035LSD

N-CHANNEL (cont.)





P-CHANNEL

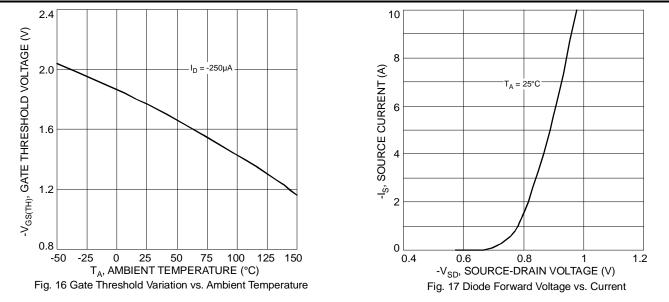




Not Recommended for New Design, Use DMC3036LSD-13

DMC3035LSD

P-CHANNEL (cont.)

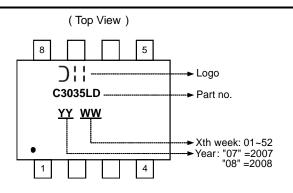


Ordering Information (Note 6)

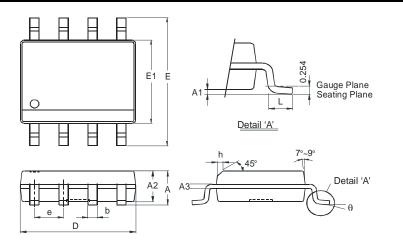
Part Number	Case	Packaging
DMC3035LSD-13	SO-8	2500/Tape & Reel

Notes: 6. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



Package Outline Dimensions

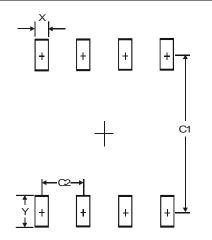


SO-8					
Dim	Min	Max			
Α	-	1.75			
A1	0.08	0.25			
A2	1.30	1.50			
A3	0.20	Тур			
b	0.3	0.5			
D	4.80	5.30			
Е	5.79	6.20			
E1	3.70	4.10			
e	1.27	Тур			
h	-	0.35			
L	0.38	1.27			
θ	0°	8°			
All Di	All Dimensions in mm				

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Suggested Pad Layout



Dimensions	Value (in mm)
Х	0.60
Y	1.55
C1	5.4
C2	1 27

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